

RAMAN IMAGING FOR SPATIALLY RESOLVED THERMAL CHARACTERIZATION OF MATERIALS AND OPERATING DEVICES

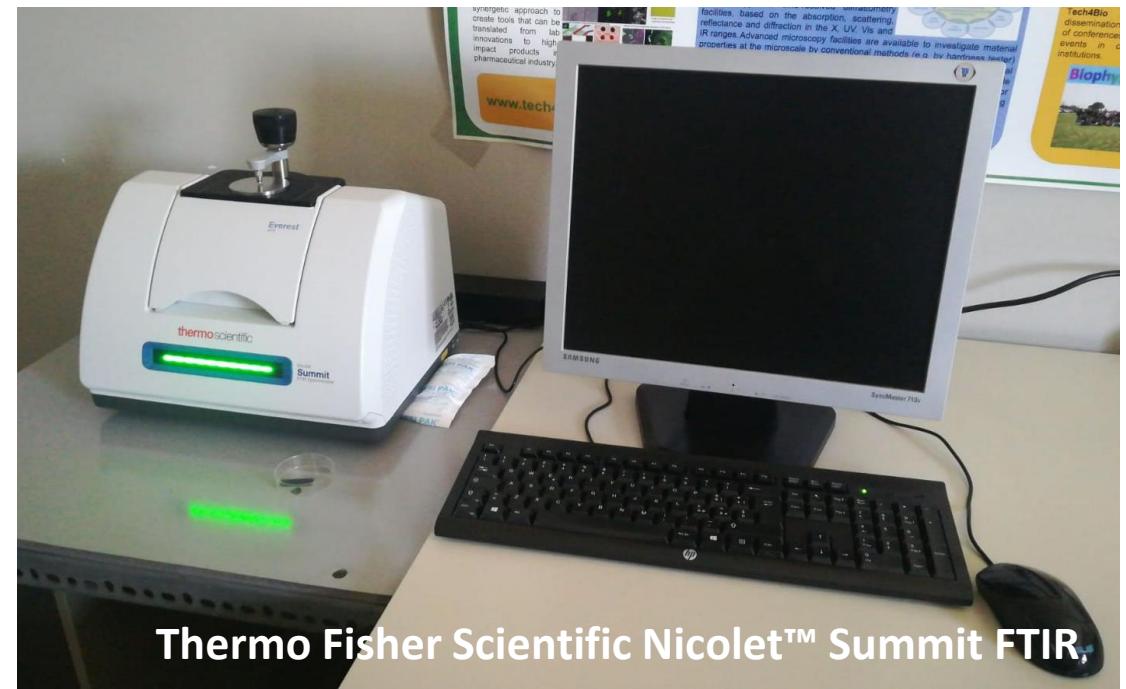
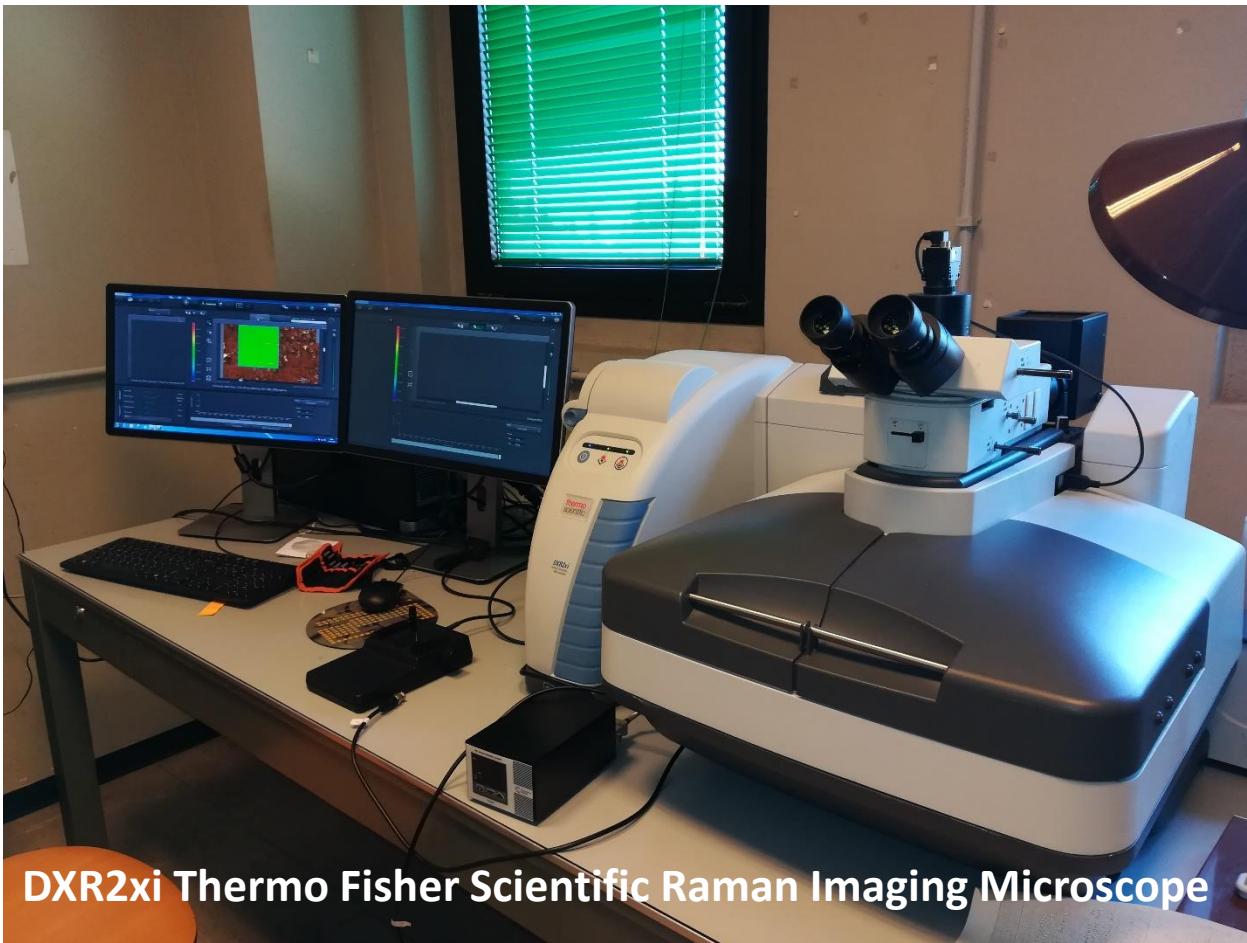
Valentina Mussi

Institute of Microelectronics and Microsystems

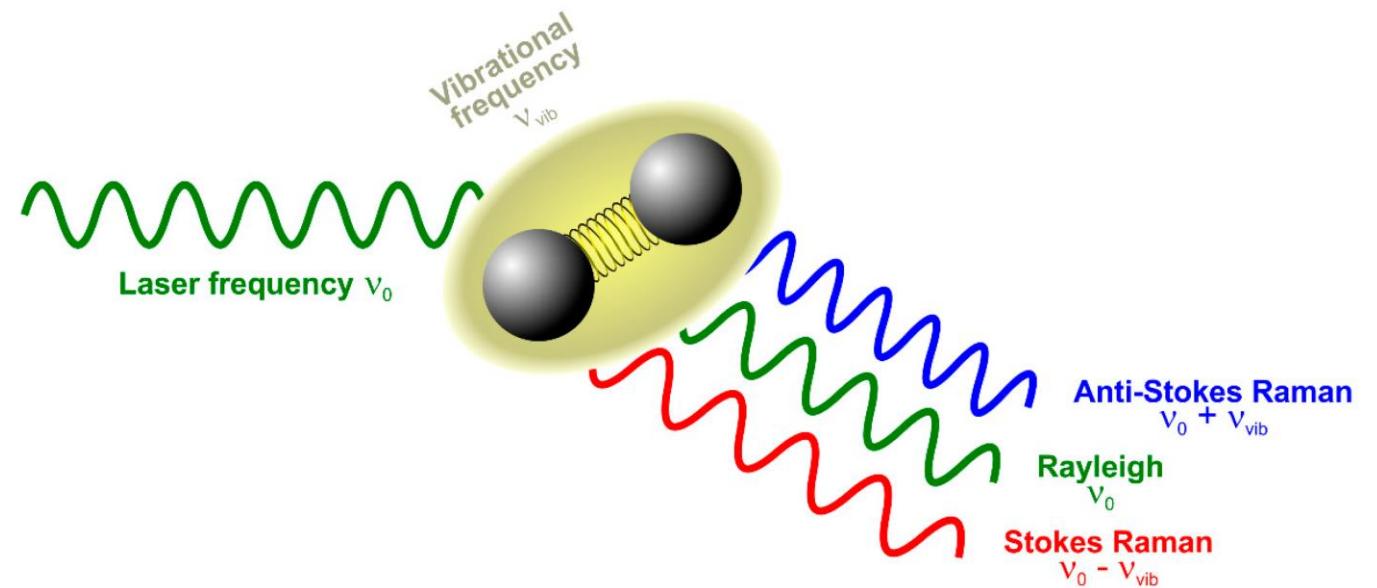
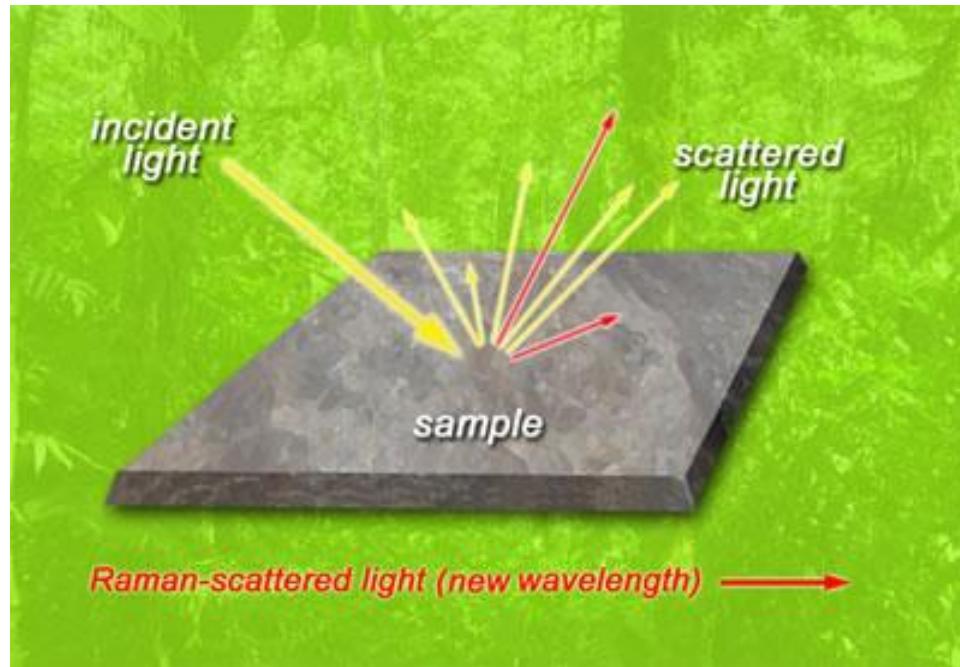
Area di Ricerca di Tor Vergata del CNR



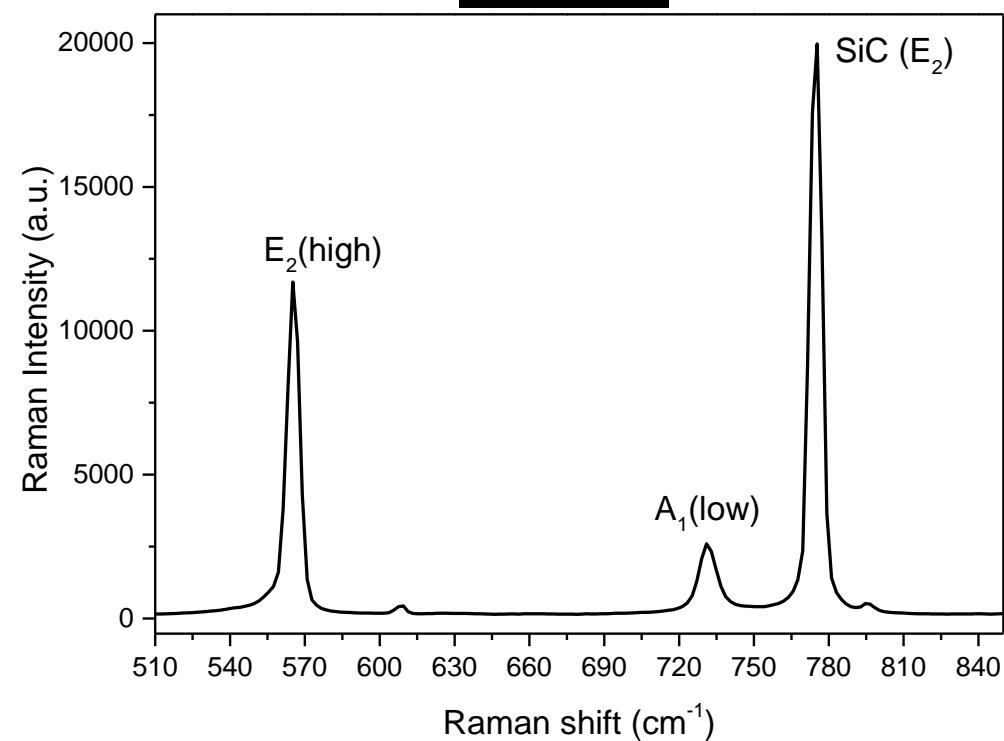
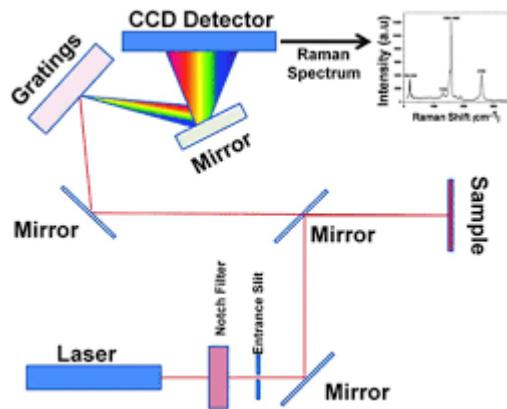
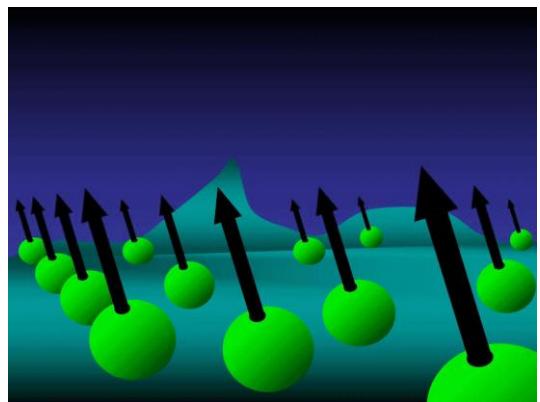
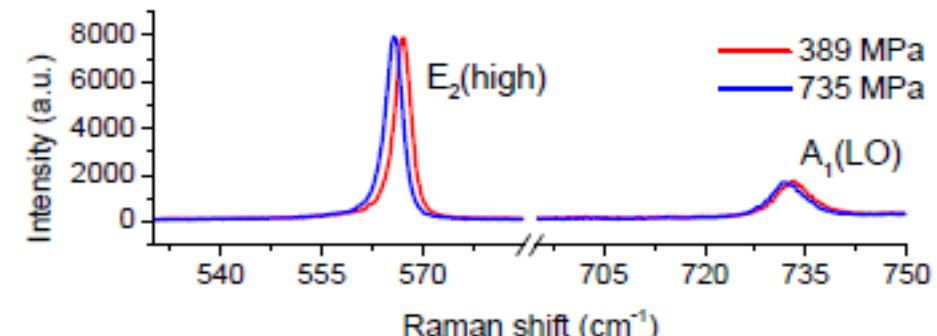
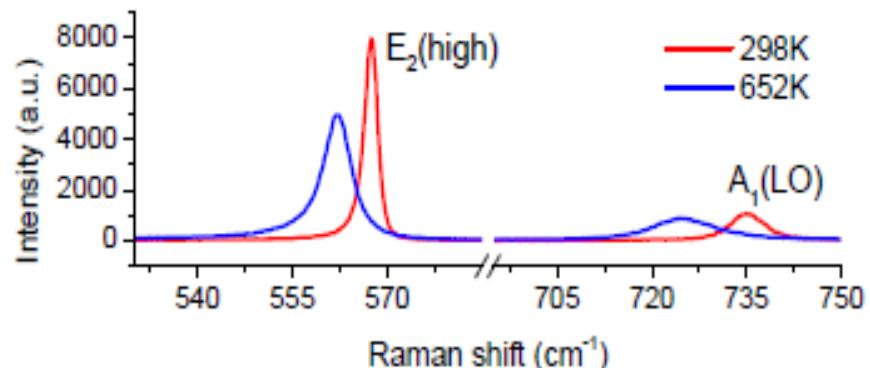
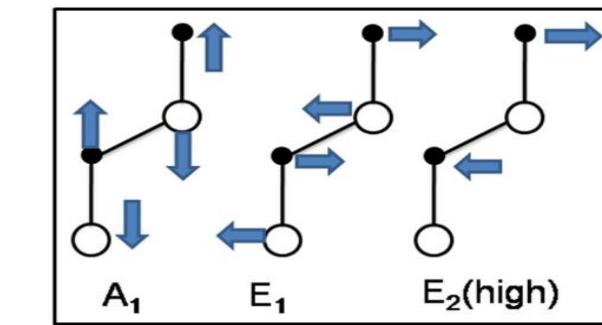
VisLab RAMAN AND FTIR FACILITIES



RAMAN (INELASTIC) SCATTERING = PHYSICO-CHEMICAL INFORMATION



RAMAN “SIGNATURE”

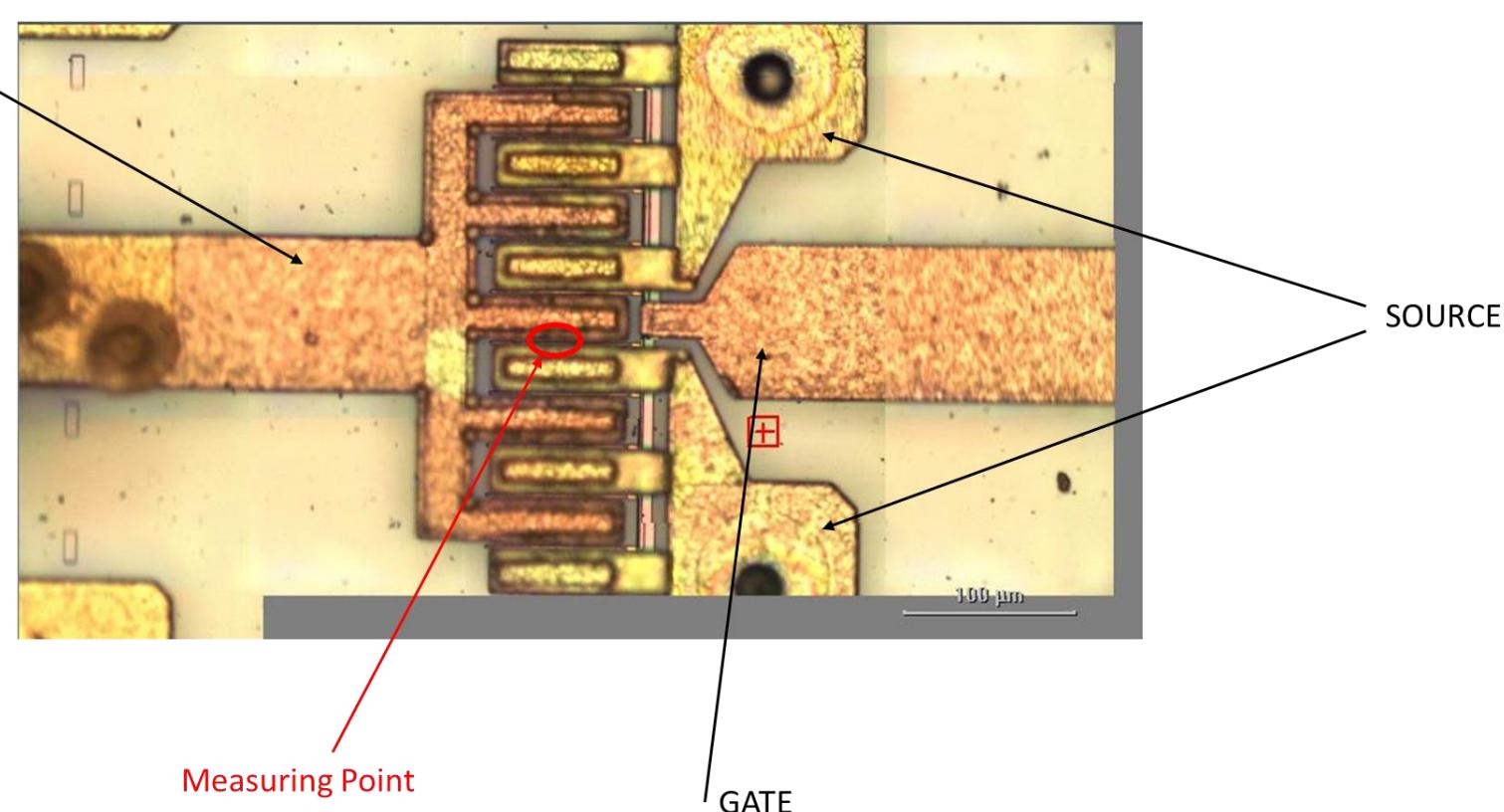



IMAGING CAPABILITIES: HEMT DEVICES

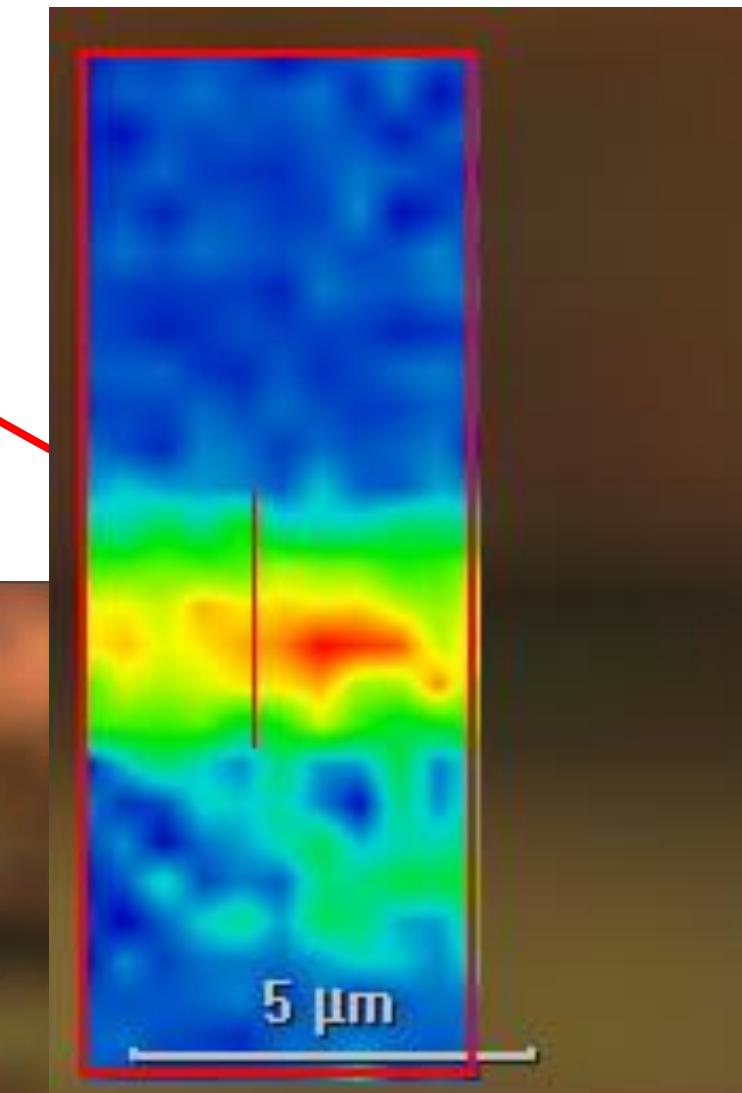
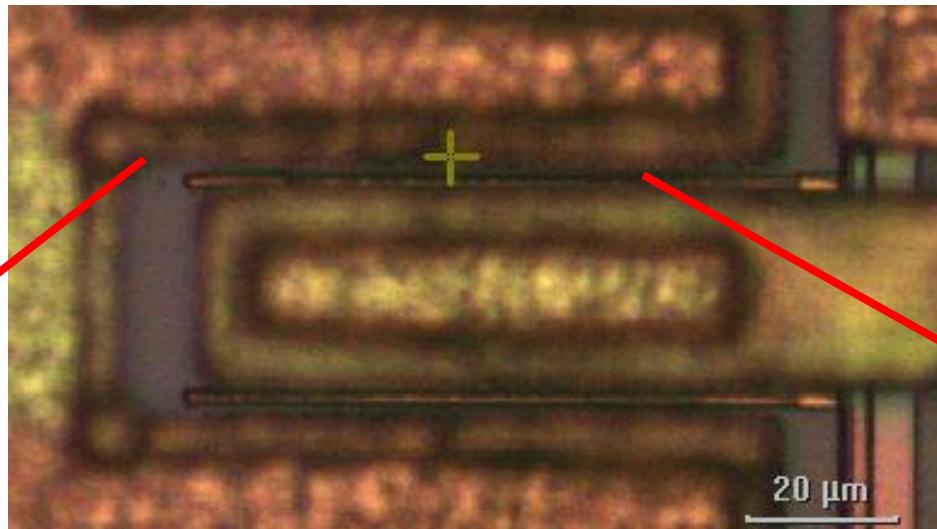
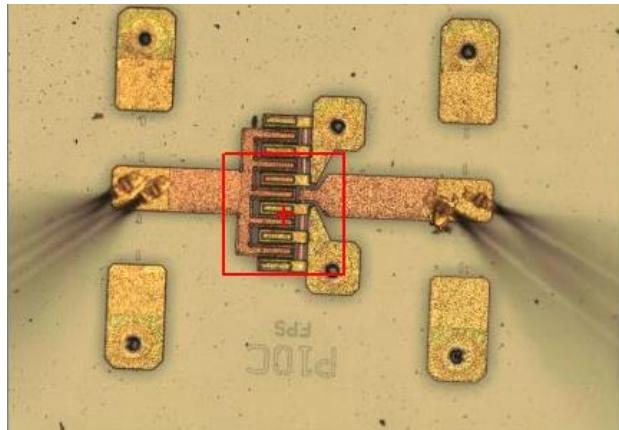
DISSIPO Project (KETs – TECNOLOGIE ABILITANTI Call, Regione Lazio)

*Ambiente Di Simulazione In-tegrato Elettromagnetico Termico e FiSico
per l'ottimizzazione delle preStazioni in dlspositivi di POtenza a Semiconduttori*

Comparison of calculated
and Raman measured
temperatute distribution
in the optically accessible
region between drain
and gate

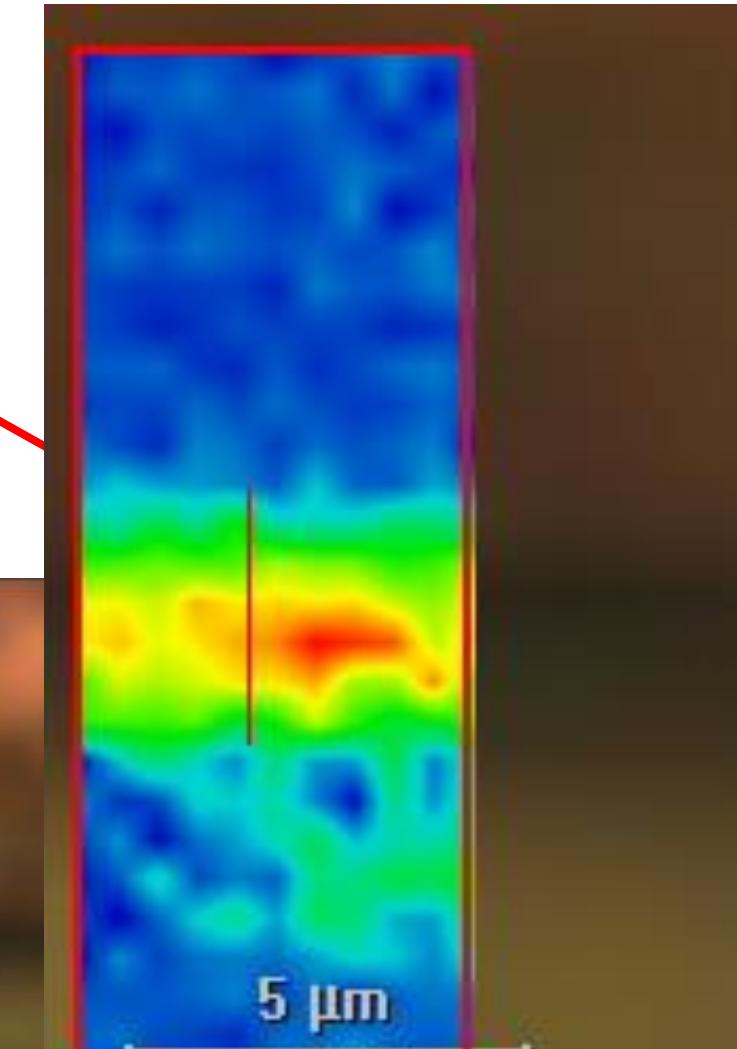
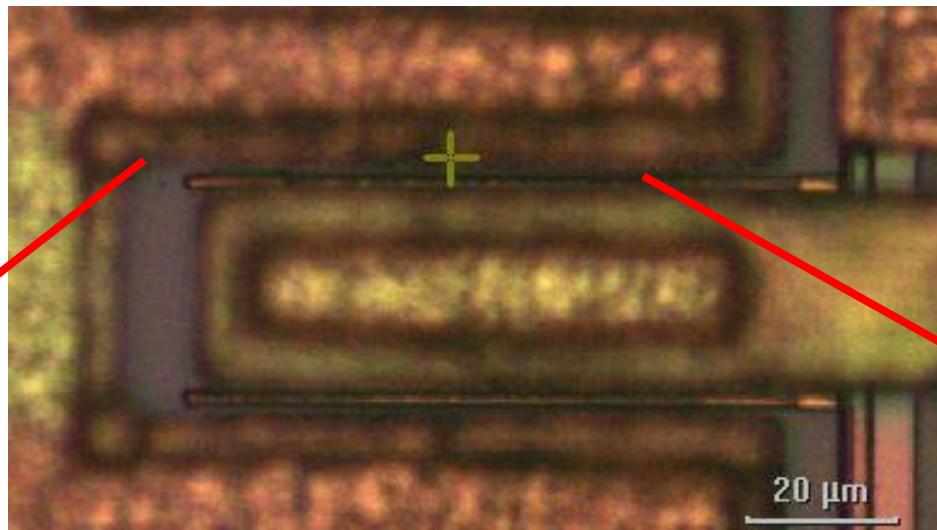
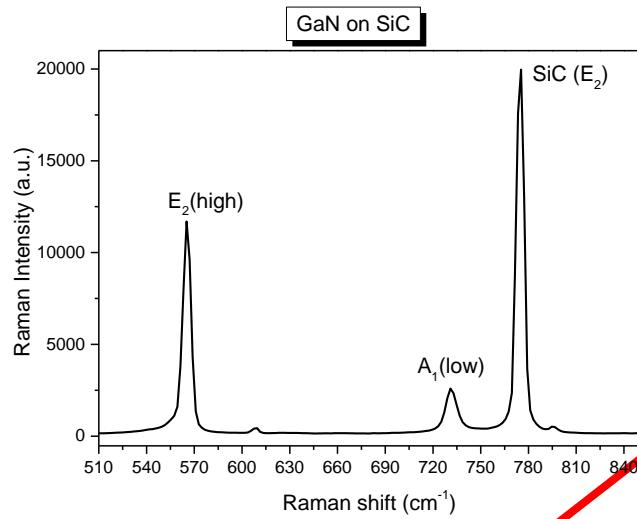


IMAGING CAPABILITIES



$P \approx 1\text{mW}$
 $\text{Spot size} = 0.8 \mu\text{m}$
 $\lambda_{\text{exc}} = 532 \text{ nm}$
LFD_OBJ 50X

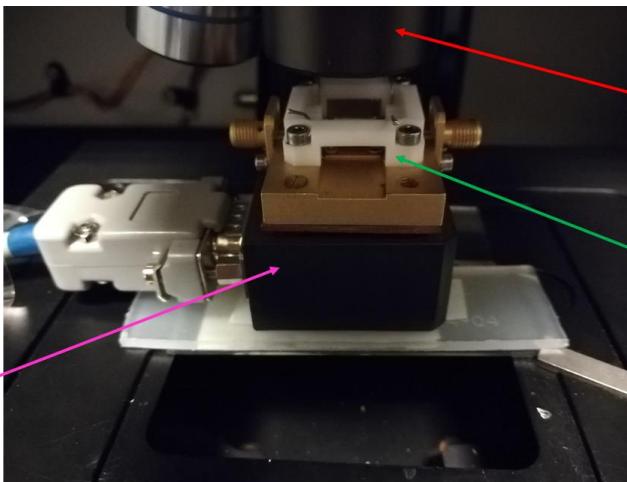
IMAGING CAPABILITIES



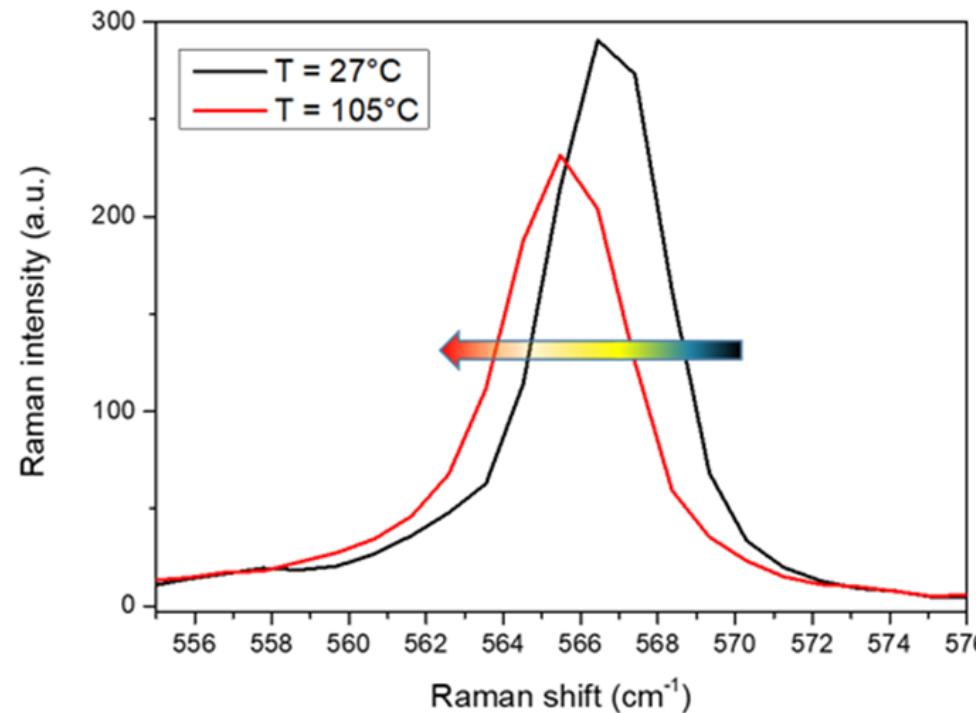
10 μm

$P \approx 1\text{ mW}$
Spot size = 0.8 μm
 $\lambda_{\text{exc}} = 532\text{ nm}$
LFD_OBJ 50X

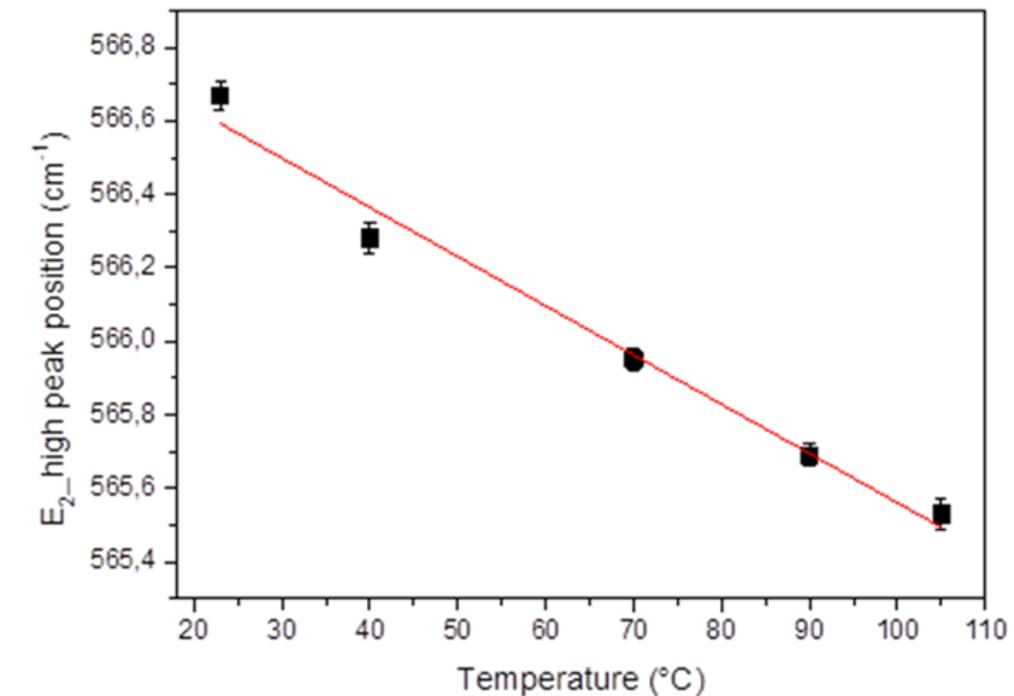
CALIBRATION



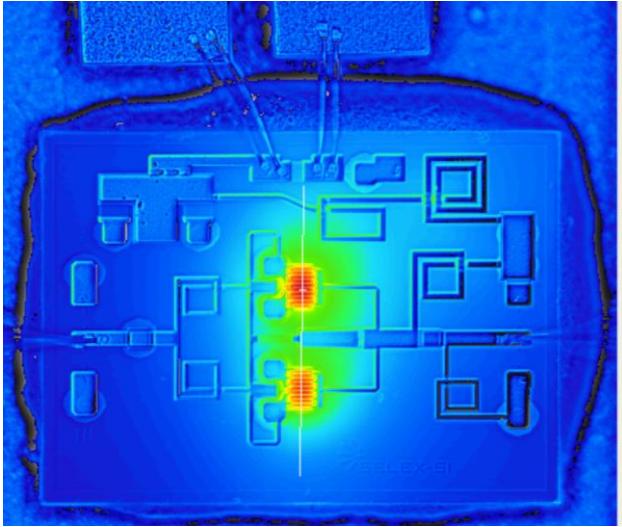
$P \approx 1\text{mW}$
 Spot size = $0.8\text{ }\mu\text{m}$
 $\lambda_{\text{exc}} = 532\text{ nm}$
 LFD_OBJ 50X



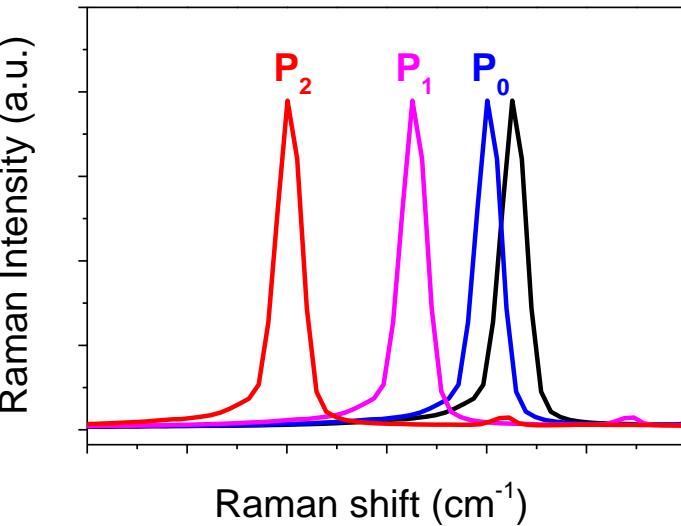
$$\Delta\omega = \omega_0 - \frac{A}{e^{\left[\frac{B\hbar\omega_0}{K_B T}\right]} - 1}$$



RAMAN THERMOGRAPHY DURING DEVICE OPERATION



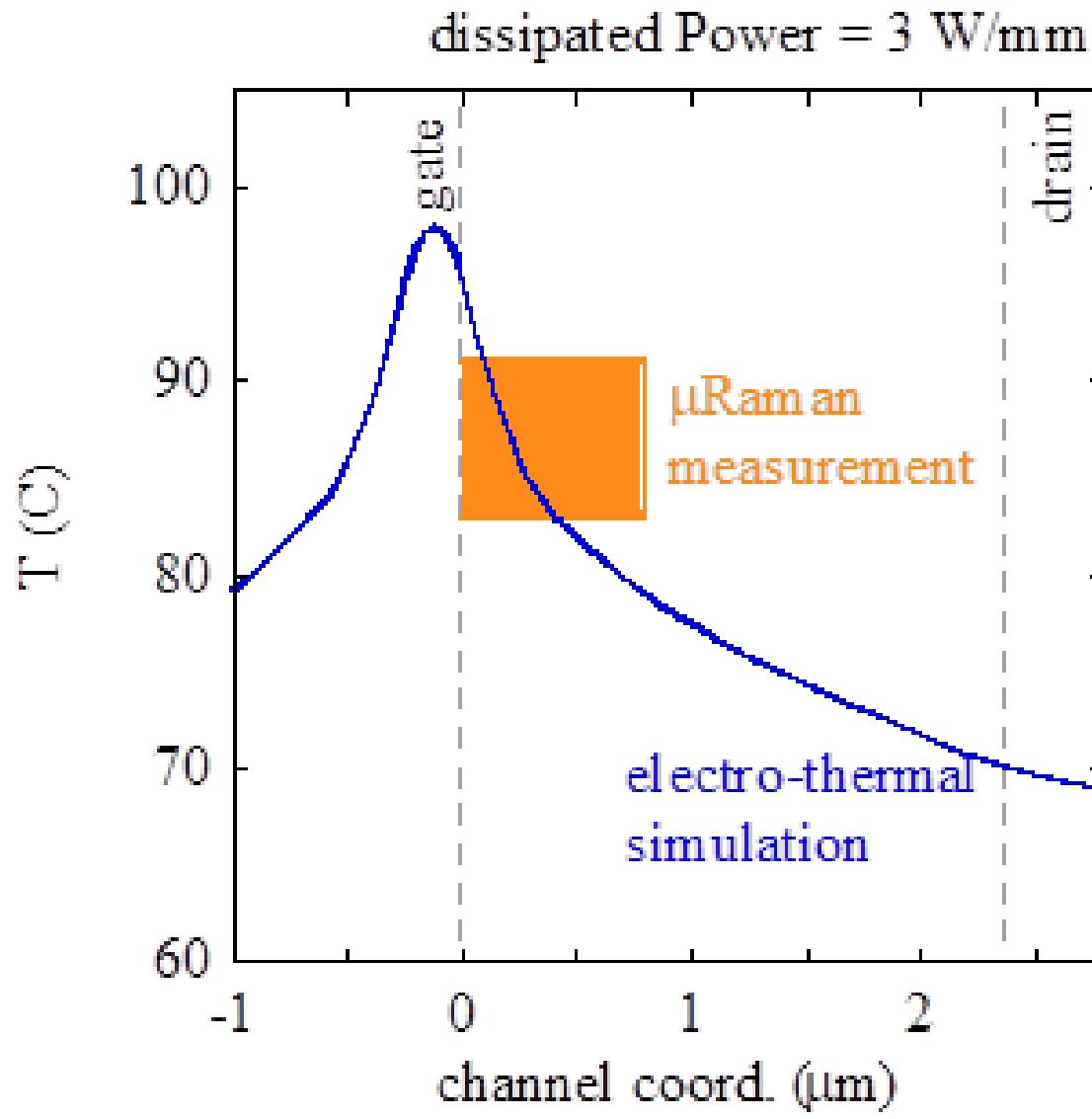
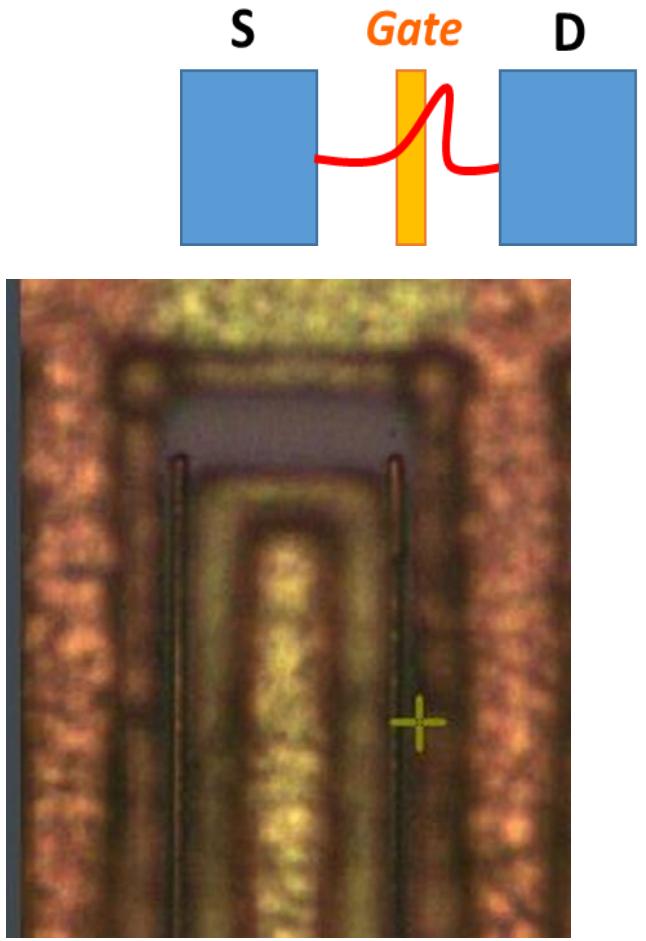
$$T = \frac{B\hbar\omega_0}{K_B Ln[1 + \frac{A}{\omega_0 - \omega}]}$$



P ≈ 1mW
Spot size = 0.8 μm
λ_{exc} = 532 nm
LFD_OBJ 50X

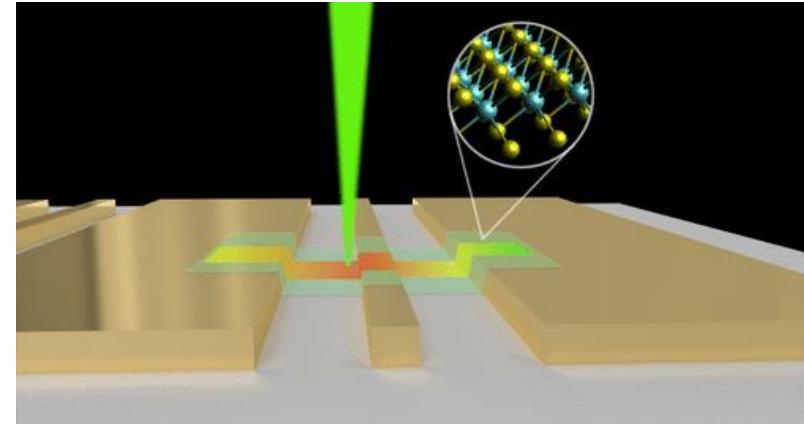
	V _{ds} V	V _{gs} V	I _{ds} mA	P diss W/mm	Δw (E ₂ _high) cm ⁻¹	Δw (A1_low) cm ⁻¹	T _{ch} °C	R _{th} °Cmm/W
P0	30	-7	1.5	-				
P1	30	-3.2	76	3	(0,49 ± 0,04)	(1,7 ± 0,1)	(87 ± 4)	(20 ± 1)
P2	30	-3.03	98.5	3,94	(0,81 ± 0,04)	(2,4 ± 0,1)	(111 ± 4)	(21 ± 1)

COMPARISON WITH SIMULATIONS



RAMAN THERMOGRAPHY@NANOMICROFAB:

- **High spatial resolution characterization ($\approx 1 \mu\text{m}$):**
- **Spatial Mapping/Imaging;**
- **Non-contact, Non-invasive (analysis during device operation);**
- **Vertical information on different layers and substrate thicknesses;**
- **No dependence on specific emissivity of different elements/materials (IR);**
- **Physico-Chemical, Thermal, Strain information;**



THANK YOU FOR YOUR ATTENTION



NANOMICROFAB
ADVANCED LAB

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